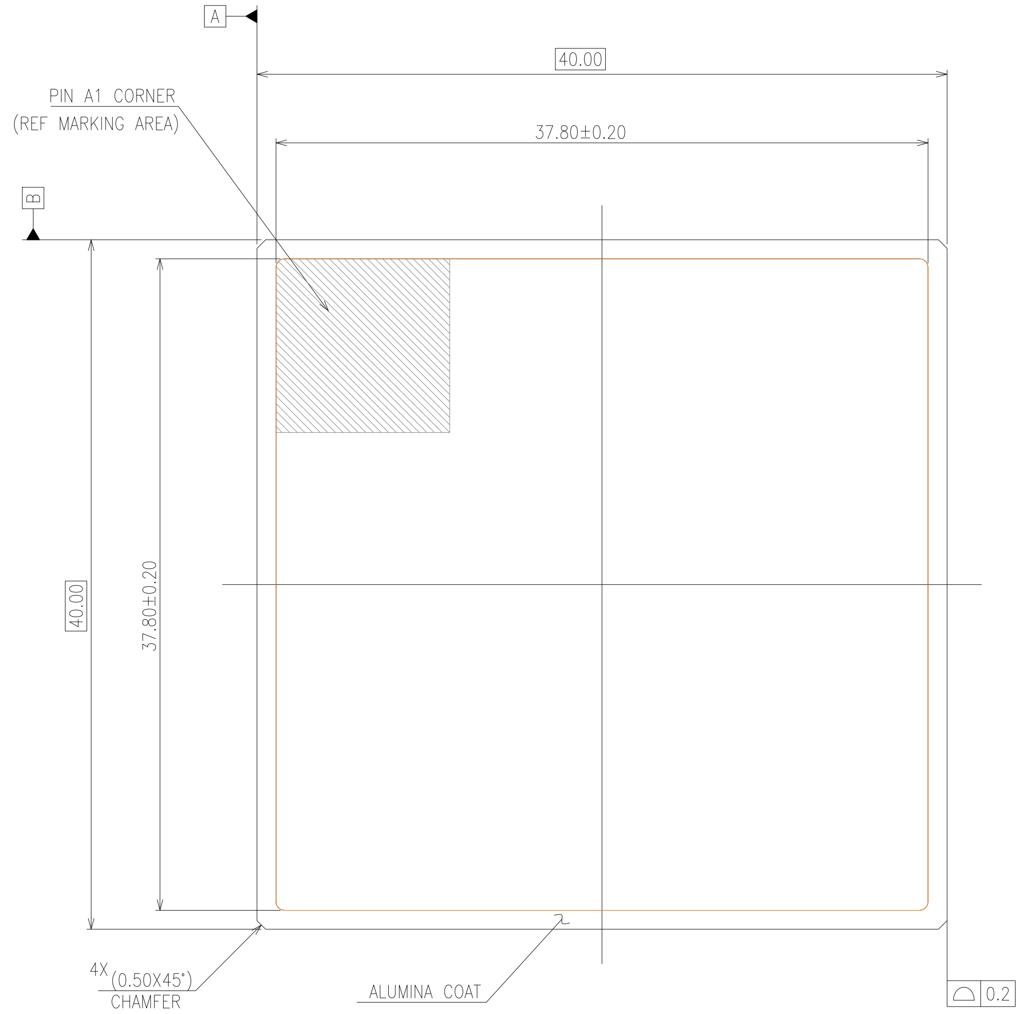
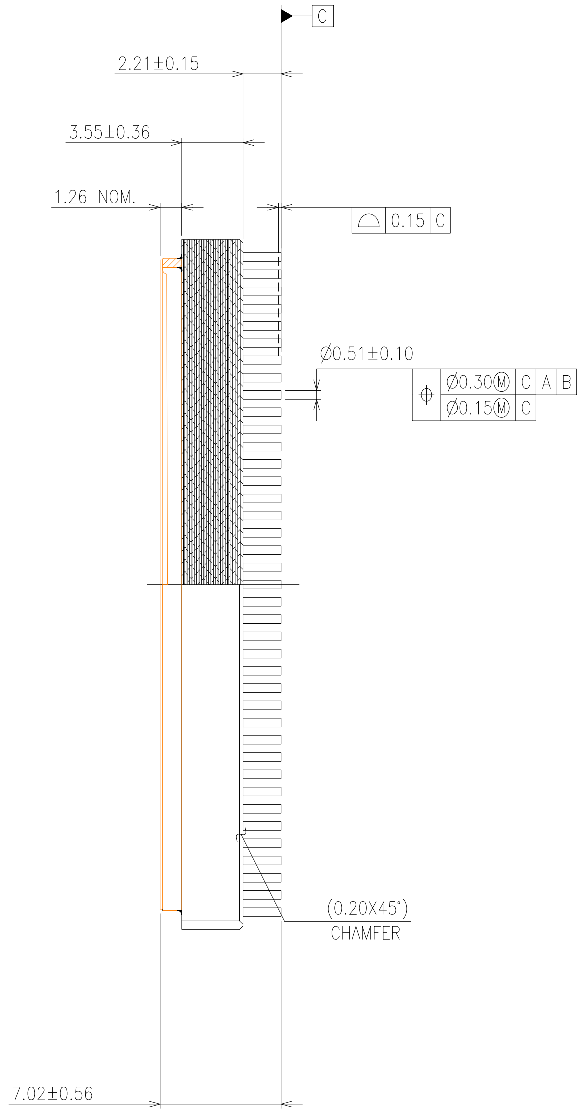
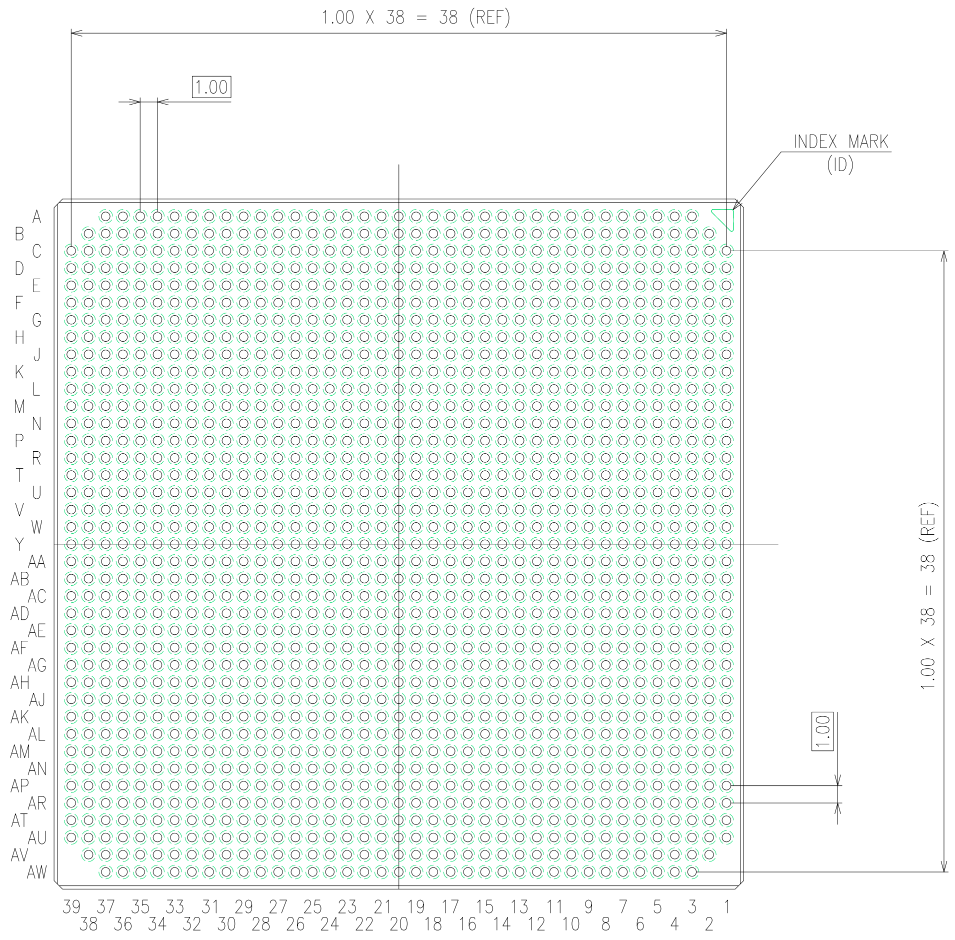
ECN NO.	REV.	DESCRIPTION OF CHANGE	EFFECTIVE DATE	ORIGINATOR
20200021	0	First release.	01/27/2020	Erwin Q







GENERAL TOLERANCE
UNLESS OTHERWISE INDICATED

DECIMAL	ANGULAR
±0.20	±1°

DIMENSIONS:
Millimeters (mm)

PROJECTION

APPROVALS		DATE
DRAWN:	Erwin Quiobo	01/27/2020
CHECKED:	Raymond Kuang	01/27/2020
ENG'R:		
RELEASED:		

Microsemi®
MICROSEMI CORPORATION, SOC GROUP
3850 N 1st St
San Jose, CA 95134

TITLE
CG1509, 40.0 MM X 40.0 MM, 1.0 MM PITCH, 1509 SOLDER COLUMNS
FLIP CHIP, CERAMIC COLUMN GRID ARRAY, PACKAGE OUTLINE DRAWING

MSCC DWG. NUMBER: 1-14-11040 REV 0
VENDOR NAME: KYOCERA
VENDOR DWG. NUMBER: KD-YB9353 REV –
LID DWG. NUMBER: ---
SCALE: NONE
SHEET 1 OF 1